

RECOR

07-11-2000

ET



To the Honorable Commissioner of Patents
documents or copy thereof.

101399267

and the attached original

1. Name of conveying party(ies):

Yasuaki Tsutsumi
Tetsuya Mieda
Masayuki Tanaka
Toshimi Kawahara
Yukio Takigawa

6-15-00

Additional name(s) of conveying party(ies) attached? ☐ Yes ☒ No

3. Nature of conveyance:

- ☒ Assignment ☐ Merger
☐ Security Agreement ☐ Change of Name
☐ Other _____

Execution Date: April 12, 2000

2. Name and address of receiving party(ies):

Toray Industries, Inc., a corporation of Japan
2-1 Nihonbashi-Muromachi 2-chome,
Chuo-ku, Tokyo 103-8666 Japan

and

Fujitsu Limited, a corporation of Japan
1-1, Kamikodanaka 4-chome, Nakahara-ku,
Kawasaki-shi, Kanagawa 211-8588 Japan

Additional name(s) and address(es) attached? ☐ Yes ☒ No

4. Application number(s) or patent number(s):

09/572,007

If this document is being filed together with a new application, the execution date of the application is:

A. Patent Application No.(s)

B. Patent No.(s)

Additional numbers attached? ☐ Yes ☒ No

5. Name and address of party to whom correspondence concerning document should be mailed:

IP Department
Schnader Harrison Segal & Lewis
1600 Market Street, 36th Floor
Philadelphia, PA 19103

6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 3.41) \$40.00

- ☒ Enclosed
☐ Authorized to be charged to deposit account

8. Deposit Account No. 13-3405

(Attach duplicate copy of this page if paying by deposit account)

07/10/2000 ASCOTT 00000215 09572007

FC:581

40.00 OP

DO NOT USE THIS SPACE

9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Austin R. Miller

Austin R. Miller

6/15/00

Name of Person Signing

Signature

Date

Total number of pages including cover sheet, attachments and document: 2

ASSIGNMENT

WHEREAS, We, Yasuaki Tsutsumi, a citizen of Japan, residing at, 10-B1-35, Sonoyama 2-chome, Otsu-shi, Shiga 520-0842 Japan; Tetsuya Mieda, a citizen of Japan residing at 208, Mizuhoryo, Hasshodoori 2-33-1, Mizuho-ku, Nagoya-shi, Aichi 467-0042 Japan; Masayuki Tanaka, a citizen of Japan, residing at 1-258, Horagai, Midori-ku, Nagoya-shi, Aichi 458-0013 Japan; Toshimi Kawahara, a citizen of Japan residing at c/o FUJITSU LIMITED of 1-1, Kamikodanaka 4-chome, Nakahara-ku, Kawasaki-shi, Kanagawa 211-8588 Japan and Yukio Takigawa, a citizen of Japan, residing at c/o FUJITSU LIMITED of 1-1, Kamikodanaka 4-chome, Nakahara-ku, Kawasaki-shi, Kanagawa 211-8588 Japan (hereinafter referred to as the undersigned), having made an invention entitled

SEMICONDUCTOR-SEALING RESIN COMPOSITION AND SEMICONDUCTOR DEVICE USING IT

the undersigned executed an application for Letters Patent of the United States of America,

WHEREAS, Toray Industries, Inc., a corporation of Japan, with offices at 2-1 Nihonbashi-Muromachi 2-chome, Chuo-ku, Tokyo 103-8666 Japan and FUJITSU LIMITED, a corporation of Japan, with offices at 1-1, Kamikodanaka 4-chome, Nakahara-ku, Kawasaki-shi, Kanagawa 211-8588 Japan; (hereinafter referred to as assignees), are desirous of acquiring the entire right, title and interest in said invention, said application and all letters patent issuing for said invention,

NOW, THEREFORE, in consideration of One Dollar (\$1.00) and of other good and valuable consideration, receipt of which is hereby acknowledged, the undersigned, intending to be legally bound, does hereby sell, assign and transfer to the assignee the entire right, title and interest, for the United States of America, its territories and possessions, and for all foreign countries, in said invention, including said patent application, all divisions and continuations thereof, all rights to claim priority based thereon, all rights to file foreign applications on said invention, and all letters patent and reissues thereof, issuing for said invention the United States of America and in any and all foreign countries.

It is agreed that the undersigned shall be legally bound, upon request of the assignee, or its successors or assigns or a legal representative thereof, to supply all information and evidence of which the undersigned has knowledge or possession relating to the making and practice of said invention, to testify in any legal proceeding relating thereto, to execute all instruments proper to patent the invention in the United States of America and foreign countries in the name of the assignee, and to execute all instruments proper to carry out the intent of this instrument. If the undersigned includes more than one individual, these obligations shall apply to all of the undersigned both individually and collectively.

The rights and property herein conveyed by the undersigned are free and clear of any encumbrance.

EXECUTED on April 12, 2000, at Otsu-shi, Shiga

The Undersigned:

Yasuaki Tsutsumi

Yasuaki Tsutsumi

Tetsuya Mieda

Tetsuya Mieda

Masayuki Tanaka

Masayuki Tanaka

Toshimi Kawahara

Toshimi Kawahara

Yukio Takigawa

Yukio Takigawa